IPC ASSOCIATION CONNE ELECTRONICS INDUS	Material Compo © Copyright 2005. If international and Pan	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and M	fg Informat	ion		
Supplier Info									,						
Company name*			Company unique ID			Uni	Unique ID Authority					Response Date*			
onsemi											2023-06-08				
Contact Name			Title - Contact			Pho	Phone - Contact*				Email - Contact*				
Product-Env-St	tewards		Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
uthorized Rep	resentative*		Title - Representative			Pho	Phone - Representative*				Email - Representative*				
Product-Env-Stewards Pro				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requ	Requester Item Number Mfr Ite		m Number Mfr Item Name			Ef	fective Date	ive Date Version Manufacturing Site			Weight*	UOM	Unit Type		
		NB3W80	3.3 V 100/133 MHz Buffer for PCIe		Iz Differential and Fan	out 20	023-06-08		F	PH1		96.47	mg	Each	
Ianufacturii	ng Proccess Informat	tion													
Terminal Plating / Grid Array Material			Cerminal Base Alloy J-STD-020 MSI		-STD-020 MSL Rating		Peak Process Body Temperature Max Tim		re Max Time at Peak	Tempera	ture Num	ber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		CU Alloy 3		1		260	C 30		30	secor	nds 3				
omments															
TTENTION: N	MSL 3 Rated item requires	Bake and D	ry Pack (afte	r electrical test)											
or more inform	nation regarding material	composition	please refer t	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaalian agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.33	mg	Supplier	Silicon (Si)	7440-21-3		2.33	mg
Die Attach	0.5	mg	Supplier	Silver (Ag)	7440-22-4		0.375	mg
			Supplier	Epoxy resins	129915-35-1		0.125	mg
Lead Frame	36.82	mg	Supplier	Silver (Ag)	7440-22-4		0.3682	mg
			Supplier	Tin (Sn)	7440-31-5		0.092	mg
			Supplier	Zinc (Zn)	7440-66-6		0.081	mg
			Supplier	Chromium (Cr)	7440-47-3		0.092	mg
			Supplier	Copper (Cu)	7440-50-8		36.1867	mg
Mold Compound-Black	54.23	mg		Epoxy resin	proprietary data		2.5488	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		5.423	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0542	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		43.6552	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.5488	mg
Plating	2.03	mg	Supplier	Tin (Sn)	7440-31-5		2.03	mg
Wire Bond	0.56	mg	Supplier	Palladium (Pd)	7440-05-3		0.0056	mg
			Supplier	Copper (Cu)	7440-50-8		0.5544	mg